Suggested Stack Up

Copper	Dielectric	Layer	Copper weight
1.4mil		L1 TOP LAYER	0.5oz Cu + 0.5oz Plate
	5mil		
0.7mil		L2 GND	0.5oz Cu
	5mil		
0.7mil		L3 MID LAYER1	0.5oz Cu
	37mil		
0.7mil		L4 MID LAYER2	0.5oz Cu
	5mil		
0.7mil		L5 PWR	0.5oz Cu
	5mil		
1.4mil		L6 BOTTOM LAYER	0.5oz Cu + 0.5oz Plate

Impedance Control	TraceWidth/Space	Impedance
Differential	4 / 8 / 4 (mil)	100 ohm 5%
Single Ended	4 (mil)	50 ohm 10%

Signal traces on L1 reference L2 plane & Signal traces on L3 reference L2 Plane
Signal traces on L4 reference L5 plane & Signal traces on L6 reference L5 Plane

* Manufacturer should change the stack up to match the impedance control base on the PCB material used.

MBCC-FMC-V-B	HKADS-13-07-HW-0201
Ref Sch: V-B	12/6/2013 11:34:20 AM
Board Thickness: 1.6mm 6 Layers FR4	

Top Overlay

Top Solder

Mechanical 1 Mechanical 2

Board shall be fabricate - Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL940V-0,
0.5 OZ Copper for External Layers & 0.5 OZ Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
Td Rating: >340 DEG C
Z Axis CTE < 3.5%
Tg > 170 DEG C (Min)

Solder Mask: SMOBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Min to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)
Finish: Electro-less Nickel Immersion Gold (ENIG), 2~8 Micro Inches Gold Over 150~250 Mirco Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.